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- Member of the Texas Instruments Widebus+™ Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4.2 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C

- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

#### description/ordering information

This 32-bit transparent D-type latch is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVC32373A is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. It can be used as four 8-bit latches, two 16-bit latches, or one 32-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### **ORDERING INFORMATION**

TA	PACKAGE	t	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C	LFBGA – GKE	Tape and reel	SN74LVC32373AGKER	NC373A	
-40 C to 65 C	LFBGA – ZKE (Pb-free)	Tape and reel	SN74LVC32373AZKER	NC373A	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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# SN74LVC32373A **32-BIT TRANSPARENT D-TYPE LATCH** WITH 3-STATE OUTPUTS SCES575 – JUNE 2004

#### **GKE OR ZKE PACKAGE** (TOP VIEW)

		1	2	3	4	5	6
Α	/	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\circ$
В		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
С		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
D		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
Е		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
F		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
G		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
н		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
J		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
K		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
L		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
M		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
N		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
Р		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
R		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
Т		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
	1						

## terminal assignments

	1	2	3	4	5	6
Α	1Q2	1Q1	1OE	1LE	1D1	1D2
В	1Q4	1Q3	GND	GND	1D3	1D4
С	1Q6	1Q5	Vcc	Vcc	1D5	1D6
D	1Q8	1Q7	GND	GND	1D7	1D8
E	2Q2	2Q1	GND	GND	2D1	2D2
F	2Q4	2Q3	VCC	VCC	2D3	2D4
G	2Q6	2Q5	GND	GND	2D5	2D6
Н	2Q7	2Q8	2OE	2LE	2D8	2D7
J	3Q2	3Q1	3OE	3LE	3D1	3D2
K	3Q4	3Q3	GND	GND	3D3	3D4
L	3Q6	3Q5	VCC	VCC	3D5	3D6
M	3Q8	3Q7	GND	GND	3D7	3D8
N	4Q2	4Q1	GND	GND	4D1	4D2
Р	4Q4	4Q3	Vcc	VCC	4D3	4D4
R	4Q6	4Q5	GND	GND	4D5	4D6
Т	4Q7	4Q8	4OE	4LE	4D8	4D7

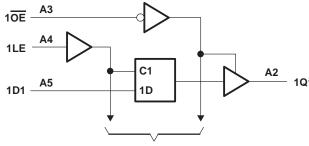
#### **FUNCTION TABLE**

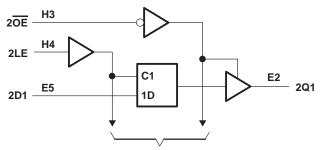
	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	$Q_0$
Н	X	X	Z



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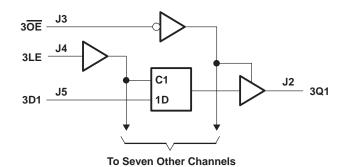
### logic diagram (positive logic)

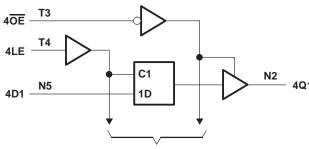




To Seven Other Channels

To Seven Other Channels





To Seven Other Channels

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The value of  $V_{\hbox{\scriptsize CC}}$  is provided in the recommended operating conditions table.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



# SN74LVC32373A 32-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
\ <u>'</u>	Complementaria	Operating	1.65	3.6	V	
$V_{CC}$	Supply voltage	Data retention only	1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		
VIL	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		
٧ı	Input voltage	•	0	5.5	V	
	0	High or low state	0	VCC	.,	
VO	Output voltage	3-state	0	5.5	V	
		V <sub>CC</sub> = 1.65 V		-4		
		V <sub>CC</sub> = 2.3 V		-8		
IOH	High-level output current	V <sub>CC</sub> = 2.7 V		-12	mA	
		V <sub>CC</sub> = 3 V	-24			
		V <sub>CC</sub> = 1.65 V		4		
		V <sub>CC</sub> = 2.3 V		8		
lOL	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA	
		V <sub>CC</sub> = 3 V		24		
Δt/Δν	Input transition rise or fall rate	·		10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	ONDITIONS	VCC	MIN	TYP <sup>†</sup>	MAX	UNIT
	I <sub>OH</sub> = -100 μA		1.65 V to 3.6 V	VCC -	0.2		
	$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
	$I_{OH} = -8 \text{ mA}$	2.3 V	1.7			V	
VOH	1 40 4		2.7 V	2.2			V
	$I_{OH} = -12 \text{ mA}$	3 V	2.4				
	I <sub>OH</sub> = -24 mA	3 V	2.2				
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2		
	$I_{OL} = 4 \text{ mA}$	I <sub>OL</sub> = 4 mA				0.45	
VOL	$I_{OL} = 8 \text{ mA}$	2.3 V			0.7	V	
	I <sub>OL</sub> = 12 mA	2.7 V			0.4		
	I <sub>OL</sub> = 24 mA	3 V			0.55		
lį	V <sub>I</sub> = 0 to 5.5 V		3.6 V			±5	μΑ
l <sub>off</sub>	$V_I$ or $V_O = 5.5 V$		0			±10	μΑ
loz	$V_0 = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±10	μΑ
	$V_I = V_{CC}$ or GND		0.01/			40	
Icc	$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\ddagger}$	IO = 0	3.6 V			40	μΑ
ΔlCC	One input at V <sub>CC</sub> – 0.6 V,	Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND		3.3 V		5		pF
Co	$V_O = V_{CC}$ or GND		3.3 V		6.5	·	pF

<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. ‡ This applies in the disabled state only.

### timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = ± 0.1	1.8 V 5 V	V <sub>CC</sub> =	$C_{C} = 2.5 \text{ V}  \pm 0.2 \text{ V} $ $V_{CC} = 2.7 \text{ V}$		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub>	Pulse duration, LE high	3.3		3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time, data before LE↓	1.6		1.2		1.7		1.7		ns
t <sub>h</sub>	Hold time, data after LE $\downarrow$	1		1.1		1.2		1.2		ns

# SN74LVC32373A **32-BIT TRANSPARENT D-TYPE LATCH** WITH 3-STATE OUTPUTS SCES575 - JUNE 2004

### switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

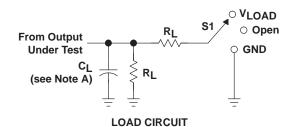
PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> =		V <sub>CC</sub> =		VCC =	2.7 V	V <sub>CC</sub> =	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	D		1.5	6.4	1	4.2	1	4.9	1.6	4.2	
<sup>t</sup> pd	LE	Q	1.5	7.1	1	4.8	1	5.3	2.1	4.6	ns
t <sub>en</sub>	ŌĒ	Q	1.5	6.7	1	4.7	1	5.7	1.3	4.7	ns
t <sub>dis</sub>	ŌĒ	Q	1.5	8.4	1	5	1	6.3	2.5	5.9	ns

## operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT	
	Power dissipation capacitance		Outputs enabled	f 40 MH	32	35	39	
	Ppd	per latch	Outputs disabled	f = 10 MHz	4	4	6	pF

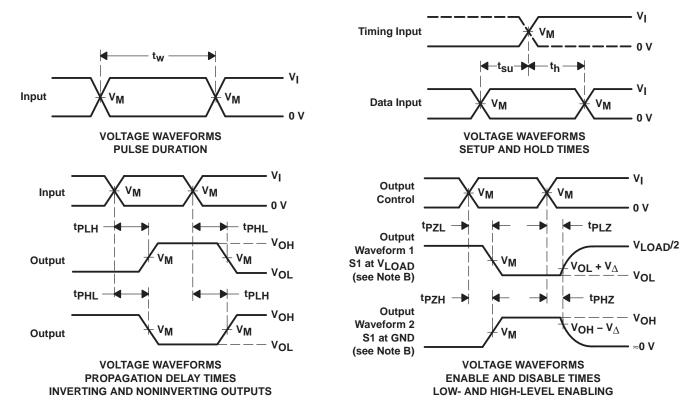


#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

.,	INPUTS		.,	V		_	.,
Vcc	٧ <sub>I</sub>	t <sub>r</sub> /t <sub>f</sub>	VM	VLOAD	CL	RL	$oldsymbol{V}_\Delta$
1.8 V $\pm$ 0.15 V	VCC	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	VCC	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×VCC	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



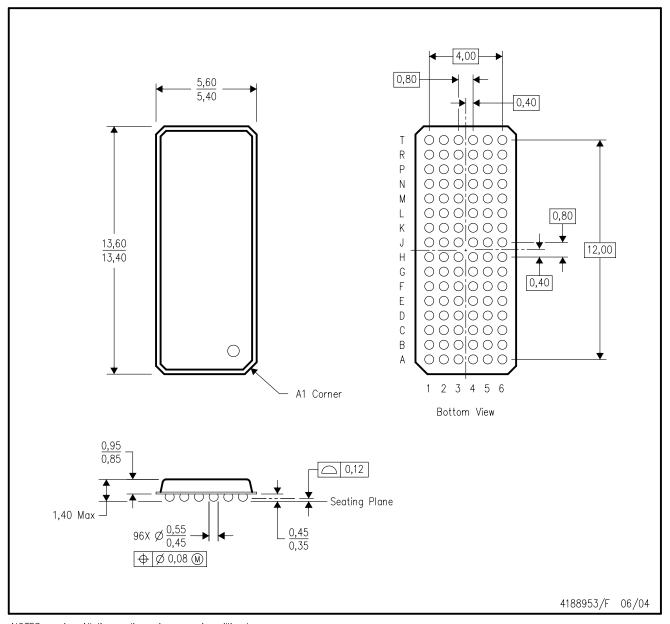
- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. tpLz and tpHz are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



# GKE (R-PBGA-N96)

## PLASTIC BALL GRID ARRAY



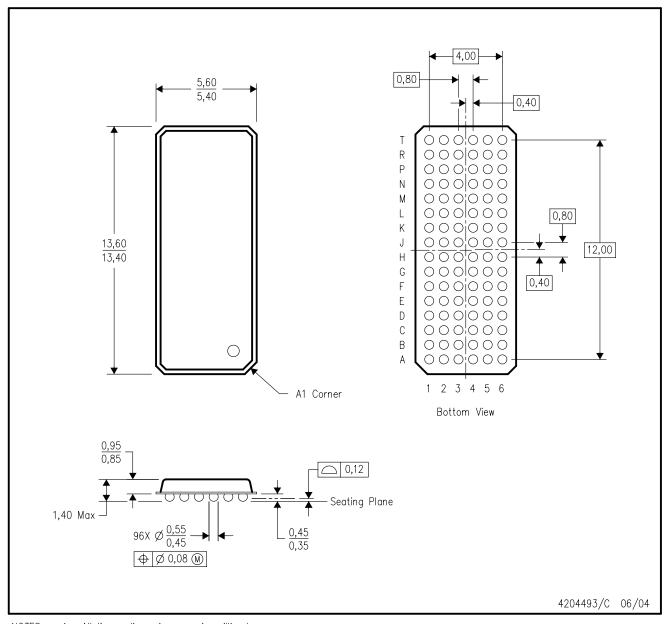
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation CC.
- D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.



# ZKE (R-PBGA-N96)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation CC.
- D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).



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